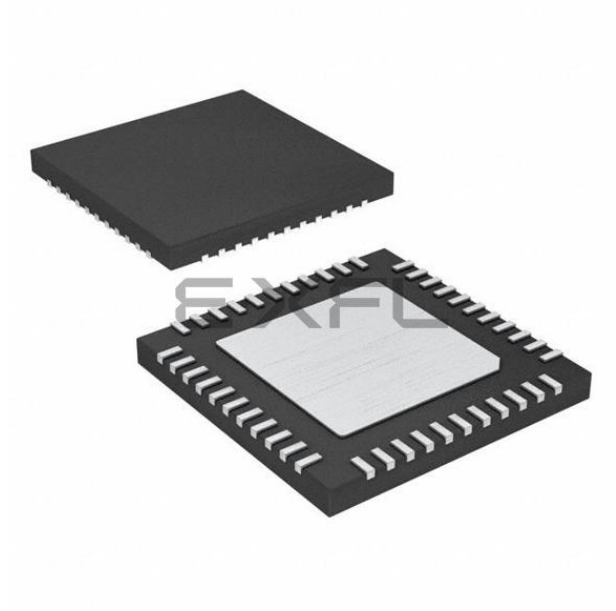

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Applications of "Embedded - Microcontrollers"

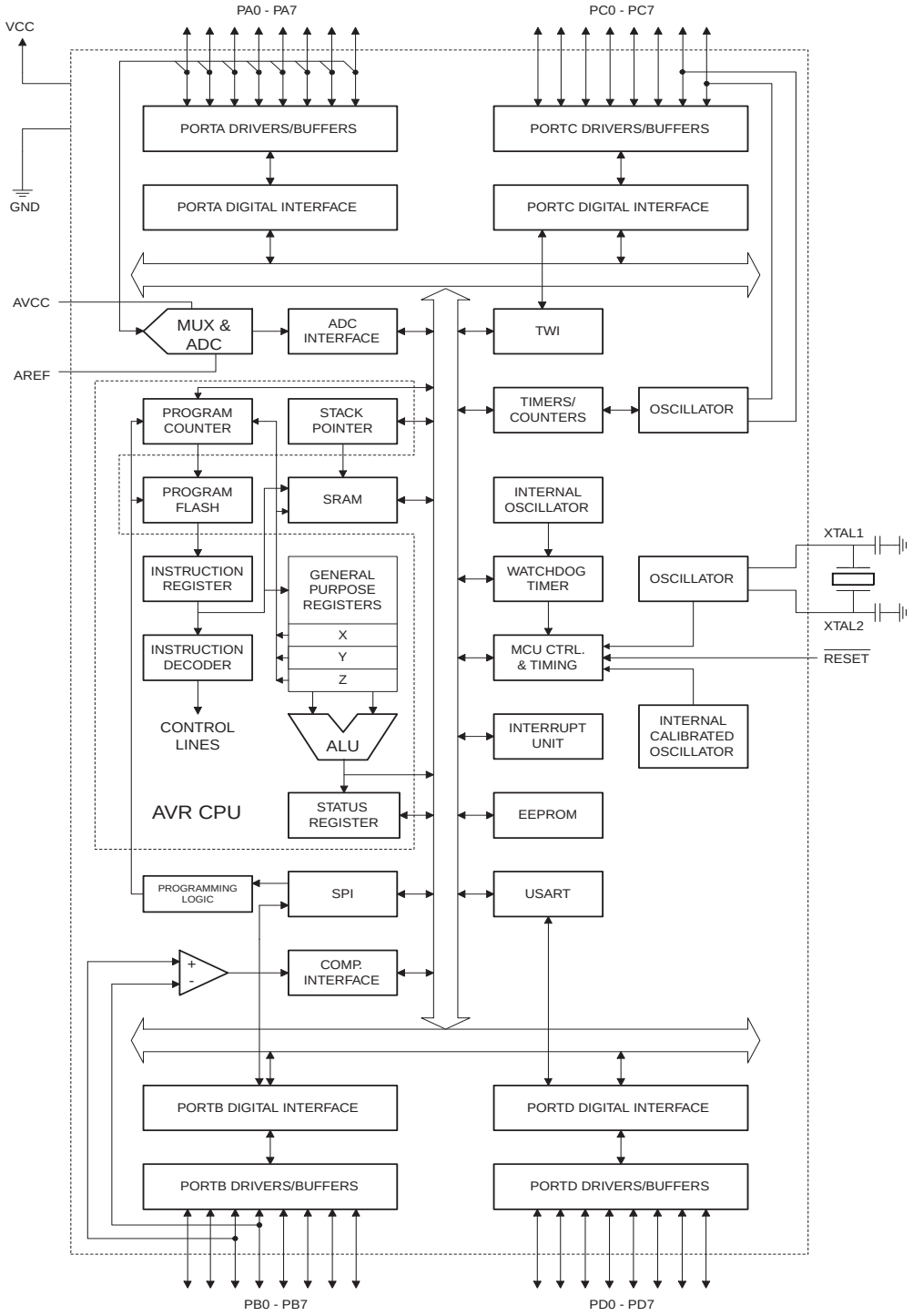
Details	
Product Status	Obsolete
Core Processor	AVR
Core Size	8-Bit
Speed	8MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	32
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFQFN Exposed Pad
Supplier Device Package	44-VQFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atmega16l-8mc

Overview

The ATmega16 is a low-power CMOS 8-bit microcontroller based on the AVR enhanced RISC architecture. By executing powerful instructions in a single clock cycle, the ATmega16 achieves throughputs approaching 1 MIPS per MHz allowing the system designer to optimize power consumption versus processing speed.

Block Diagram

Figure 2. Block Diagram



The next code examples show assembly and C functions for reading the EEPROM. The examples assume that interrupts are controlled so that no interrupts will occur during execution of these functions.

Assembly Code Example

```
EEPROM_read:
  ; Wait for completion of previous write
  sbic EECR,EEWE
  rjmp EEPROM_read
  ; Set up address (r18:r17) in address register
  out  EEARH, r18
  out  EEARL, r17
  ; Start eeprom read by writing EERE
  sbi  EECR,EERE
  ; Read data from data register
  in   r16,EEDR
  ret
```

C Code Example

```
unsigned char EEPROM_read(unsigned int uiAddress)
{
  /* Wait for completion of previous write */
  while(EECR & (1<<EEWE))
    ;
  /* Set up address register */
  EEAR = uiAddress;
  /* Start eeprom read by writing EERE */
  EECR |= (1<<EERE);
  /* Return data from data register */
  return EEDR;
}
```

EEPROM Write During Power-down Sleep Mode

When entering Power-down Sleep mode while an EEPROM write operation is active, the EEPROM write operation will continue, and will complete before the Write Access time has passed. However, when the write operation is completed, the Oscillator continues running, and as a consequence, the device does not enter Power-down entirely. It is therefore recommended to verify that the EEPROM write operation is completed before entering Power-down.

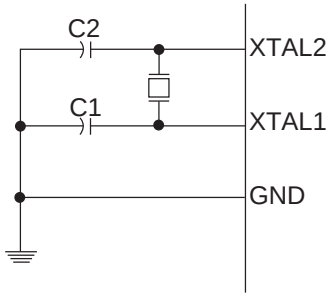
Preventing EEPROM Corruption

During periods of low $V_{CC,}$ the EEPROM data can be corrupted because the supply voltage is too low for the CPU and the EEPROM to operate properly. These issues are the same as for board level systems using EEPROM, and the same design solutions should be applied.

An EEPROM data corruption can be caused by two situations when the voltage is too low. First, a regular write sequence to the EEPROM requires a minimum voltage to operate correctly. Secondly, the CPU itself can execute instructions incorrectly, if the supply voltage is too low.

choosing capacitors for use with crystals are given in Table 4. For ceramic resonators, the capacitor values given by the manufacturer should be used.

Figure 12. Crystal Oscillator Connections



The Oscillator can operate in three different modes, each optimized for a specific frequency range. The operating mode is selected by the fuses CKSEL3..1 as shown in Table 4.

Table 4. Crystal Oscillator Operating Modes

CKOPT	CKSEL3..1	Frequency Range (MHz)	Recommended Range for Capacitors C1 and C2 for Use with Crystals (pF)
1	101[1]	0.4 - 0.9	–
1	110	0.9 - 3.0	12 - 22
1	111	3.0 - 8.0	12 - 22
0	101, 110, 111	1.0 ≤	12 - 22

Note: 1. This option should not be used with crystals, only with ceramic resonators.

When this Oscillator is selected, start-up times are determined by the SUT Fuses as shown in Table 8.

Table 8. Start-up Times for the External RC Oscillator Clock Selection

SUT1..0	Start-up Time from Power-down and Power-save	Additional Delay from Reset (V_{CC} = 5.0V)	Recommended Usage
00	18 CK	–	BOD enabled
01	18 CK	4.1 ms	Fast rising power
10	18 CK	65 ms	Slowly rising power
11	6 CK(1)	4.1 ms	Fast rising power or BOD enabled

Note: 1. This option should not be used when operating close to the maximum frequency of the device.

Calibrated Internal RC Oscillator

The Calibrated Internal RC Oscillator provides a fixed 1.0 MHz, 2.0 MHz, 4.0 MHz, or 8.0 MHz clock. All frequencies are nominal values at 5V and 25°C. This clock may be selected as the system-clock by programming the CKSEL Fuses as shown in Table 9. If selected, it will operate with no external components. The CKOPT Fuse should always be unpro-grammed when using this clock option. During Reset, hardware loads the calibration byte into the OSCCAL Register and thereby automatically calibrates the RC Oscillator. At 5V, 25°C and 1.0 MHz, 2.0 MHz, 4.0 MHz or 8.0 MHz Oscillator frequency selected, this calibration gives a frequency within ±3% of the nominal frequency. Using calibration methods as described in application notes available at www.atmel.com/avr it is possible to achieve ±1% accuracy at any given V_{CC} and Temperature. When this Oscillator is used as the Chip Clock, the Watchdog Oscillator will still be used for the Watchdog Timer and for the reset time-out. For more information on the pre-programmed calibration value, see the section “Calibration Byte” on page 261.

Table 9. Internal Calibrated RC Oscillator Operating Modes

CKSEL3..0	Nominal Frequency (MHz)
0001(1)	1.0
0010	2.0
0011	4.0
0100	8.0

Note: 1. The device is shipped with this option selected.

When this Oscillator is selected, start-up times are determined by the SUT Fuses as shown in Table 10. XTAL1 and XTAL2 should be left unconnected (NC).

Table 10. Start-up Times for the Internal Calibrated RC Oscillator Clock Selection

SUT1..0	Start-up Time from Power-down and Power-save	Additional Delay from Reset (V_{CC} = 5.0V)	Recommended Usage
00	6 CK	–	BOD enabled
01	6 CK	4.1 ms	Fast rising power
10(1)	6 CK	65 ms	Slowly rising power
11	Reserved		

Note: 1. The device is shipped with this option selected.

- **Bit 1, 0 – ISC01, ISC00: Interrupt Sense Control 0 Bit 1 and Bit 0**

The External Interrupt 0 is activated by the external pin INT0 if the SREG I-flag and the corresponding interrupt mask are set. The level and edges on the external INT0 pin that activate the interrupt are defined in Table 35. The value on the INT0 pin is sampled before detecting edges. If edge or toggle interrupt is selected, pulses that last longer than one clock period will generate an interrupt. Shorter pulses are not guaranteed to generate an interrupt. If low level interrupt is selected, the low level must be held until the completion of the currently executing instruction to generate an interrupt.

Table 35. Interrupt 0 Sense Control

ISC01	ISC00	Description
0	0	The low level of INT0 generates an interrupt request.
0	1	Any logical change on INT0 generates an interrupt request.
1	0	The falling edge of INT0 generates an interrupt request.
1	1	The rising edge of INT0 generates an interrupt request.

MCU Control and Status Register – MCUCSR

Bit	7	6	5	4	3	2	1	0	
	JTD	ISC2	–	JTRF	WDRF	BORF	EXTRF	PORF	MCUCSR
Read/Write	R/W	R/W	R	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	See Bit Description					

- **Bit 6 – ISC2: Interrupt Sense Control 2**

The Asynchronous External Interrupt 2 is activated by the external pin INT2 if the SREG I-bit and the corresponding interrupt mask in GICR are set. If ISC2 is written to zero, a falling edge on INT2 activates the interrupt. If ISC2 is written to one, a rising edge on INT2 activates the interrupt. Edges on INT2 are registered asynchronously. Pulses on INT2 wider than the minimum pulse width given in Table 36 will generate an interrupt. Shorter pulses are not guaranteed to generate an interrupt. When changing the ISC2 bit, an interrupt can occur. Therefore, it is recommended to first disable INT2 by clearing its Interrupt Enable bit in the GICR Register. Then, the ISC2 bit can be changed. Finally, the INT2 Interrupt Flag should be cleared by writing a logical one to its Interrupt Flag bit (INTF2) in the GIFR Register before the interrupt is re-enabled.

Table 36. Asynchronous External Interrupt Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Units
t_{INT}	Minimum pulse width for asynchronous external interrupt			50		ns

General Interrupt Control Register – GICR

Bit	7	6	5	4	3	2	1	0	
	INT1	INT0	INT2	–	–	–	IVSEL	IVCE	GICR
Read/Write	R/W	R/W	R/W	R	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7 – INT1: External Interrupt Request 1 Enable**

When the INT1 bit is set (one) and the I-bit in the Status Register (SREG) is set (one), the external pin interrupt is enabled. The Interrupt Sense Control1 bits 1/0 (ISC11 and ISC10) in the MCU General Control Register (MCUCR) define whether the External Interrupt is activated on rising

Figure 36. Timer/Counter Timing Diagram, Setting of OCF0, with Prescaler ($f_{clk\_I/O}/8$)

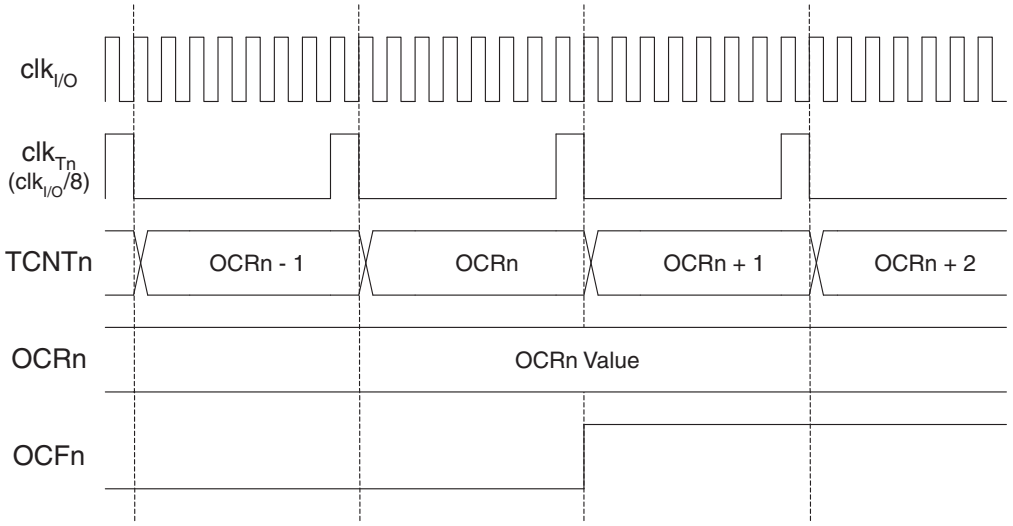
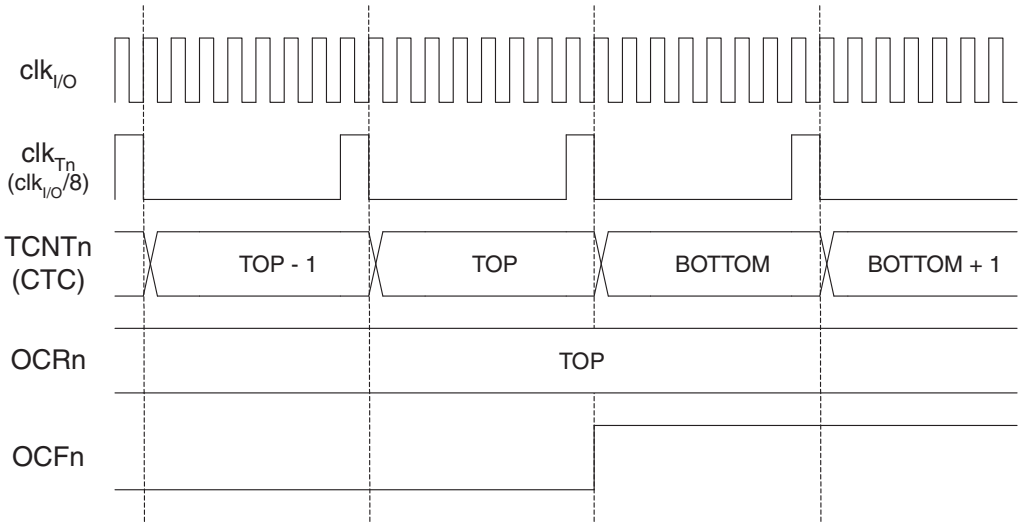


Figure 37 shows the setting of OCF0 and the clearing of TCNT0 in CTC mode.

Figure 37. Timer/Counter Timing Diagram, Clear Timer on Compare Match Mode, with Prescaler ($f_{clk\_I/O}/8$)



Accessing 16-bit Registers

The TCNT1, OCR1A/B, and ICR1 are 16-bit registers that can be accessed by the AVR CPU via the 8-bit data bus. The 16-bit register must be byte accessed using two read or write operations. Each 16-bit timer has a single 8-bit register for temporary storing of the High byte of the 16-bit access. The same temporary register is shared between all 16-bit registers within each 16-bit timer. Accessing the Low byte triggers the 16-bit read or write operation. When the Low byte of a 16-bit register is written by the CPU, the High byte stored in the temporary register, and the Low byte written are both copied into the 16-bit register in the same clock cycle. When the Low byte of a 16-bit register is read by the CPU, the High byte of the 16-bit register is copied into the temporary register in the same clock cycle as the Low byte is read.

Not all 16-bit accesses uses the temporary register for the High byte. Reading the OCR1A/B 16-bit registers does not involve using the temporary register.

To do a 16-bit write, *the High byte must be written before the Low byte*. For a 16-bit read, *the Low byte must be read before the High byte*.

The following code examples show how to access the 16-bit Timer Registers assuming that no interrupts updates the temporary register. The same principle can be used directly for accessing the OCR1A/B and ICR1 Registers. Note that when using “C”, the compiler handles the 16-bit access.

Assembly Code Example[1]

```
...
; Set TCNT1 to 0x01FF
ldi r17,0x01
ldi r16,0xFF
out TCNT1H,r17
out TCNT1L,r16
; Read TCNT1 into r17:r16
in  r16,TCNT1L
in  r17,TCNT1H
...
```

C Code Example[1]

```
unsigned int i;
...
/* Set TCNT1 to 0x01FF */
TCNT1 = 0x1FF;
/* Read TCNT1 into i */
i = TCNT1;
...
```

Note: 1. See “About Code Examples” on page 7.

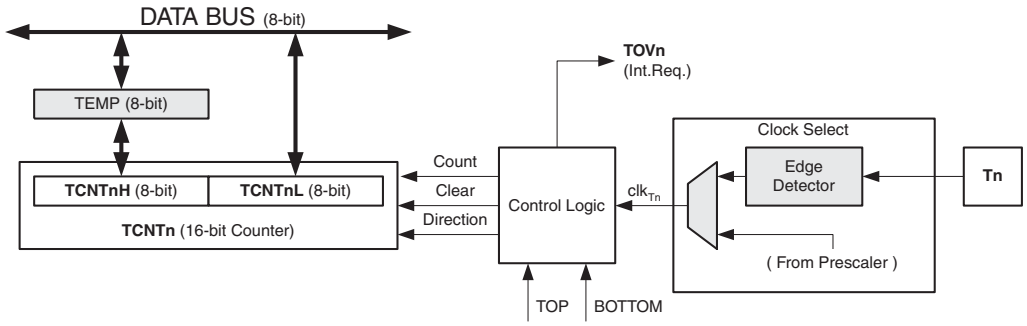
The assembly code example returns the TCNT1 value in the r17:r16 register pair.

It is important to notice that accessing 16-bit registers are atomic operations. If an interrupt occurs between the two instructions accessing the 16-bit register, and the interrupt code updates the temporary register by accessing the same or any other of the 16-bit Timer Registers, then the result of the access outside the interrupt will be corrupted. Therefore, when both the main code and the interrupt code update the temporary register, the main code must disable the interrupts during the 16-bit access.

Counter Unit

The main part of the 16-bit Timer/Counter is the programmable 16-bit bi-directional counter unit. Figure 41 shows a block diagram of the counter and its surroundings.

Figure 41. Counter Unit Block Diagram



Signal description (internal signals):

Count	Increment or decrement TCNT1 by 1.
Direction	Select between increment and decrement.
Clear	Clear TCNT1 (set all bits to zero).
clk_{T1}	Timer/Counter clock.
TOP	Signalize that TCNT1 has reached maximum value.
BOTTOM	Signalize that TCNT1 has reached minimum value (zero).

The 16-bit counter is mapped into two 8-bit I/O memory locations: *Counter High* (TCNT1H) containing the upper eight bits of the counter, and *Counter Low* (TCNT1L) containing the lower 8 bits. The TCNT1H Register can only be indirectly accessed by the CPU. When the CPU does an access to the TCNT1H I/O location, the CPU accesses the High byte temporary register (TEMP). The temporary register is updated with the TCNT1H value when the TCNT1L is read, and TCNT1H is updated with the temporary register value when TCNT1L is written. This allows the CPU to read or write the entire 16-bit counter value within one clock cycle via the 8-bit data bus. It is important to notice that there are special cases of writing to the TCNT1 Register when the counter is counting that will give unpredictable results. The special cases are described in the sections where they are of importance.

Depending on the mode of operation used, the counter is cleared, incremented, or decremented at each *timer clock* (clk_{T1}). The clk_{T1} can be generated from an external or internal clock source, selected by the *Clock Select* bits (CS12:0). When no clock source is selected (CS12:0 = 0) the timer is stopped. However, the TCNT1 value can be accessed by the CPU, independent of whether clk_{T1} is present or not. A CPU write overrides (has priority over) all counter clear or count operations.

The counting sequence is determined by the setting of the *Waveform Generation Mode* bits (WGM13:0) located in the *Timer/Counter Control Registers* A and B (TCCR1A and TCCR1B). There are close connections between how the counter behaves (counts) and how waveforms are generated on the Output Compare outputs OC1x. For more details about advanced counting sequences and waveform generation, see “Modes of Operation” on page 101.

The *Timer/Counter Overflow* (TOV1) Flag is set according to the mode of operation selected by the WGM13:0 bits. TOV1 can be used for generating a CPU interrupt.

$\overline{SS}$ Pin Functionality

Slave Mode

When the SPI is configured as a Slave, the Slave Select ($\overline{SS}$) pin is always input. When $\overline{SS}$ is held low, the SPI is activated, and MISO becomes an output if configured so by the user. All other pins are inputs. When $\overline{SS}$ is driven high, all pins are inputs except MISO which can be user configured as an output, and the SPI is passive, which means that it will not receive incoming data. Note that the SPI logic will be reset once the $\overline{SS}$ pin is driven high.

The $\overline{SS}$ pin is useful for packet/byte synchronization to keep the Slave Bit Counter synchronous with the Master Clock generator. When the $\overline{SS}$ pin is driven high, the SPI Slave will immediately reset the send and receive logic, and drop any partially received data in the Shift Register.

Master Mode

When the SPI is configured as a Master (MSTR in SPCR is set), the user can determine the direction of the $\overline{SS}$ pin.

If $\overline{SS}$ is configured as an output, the pin is a general output pin which does not affect the SPI system. Typically, the pin will be driving the $\overline{SS}$ pin of the SPI Slave.

If $\overline{SS}$ is configured as an input, it must be held high to ensure Master SPI operation. If the $\overline{SS}$ pin is driven low by peripheral circuitry when the SPI is configured as a Master with the $\overline{SS}$ pin defined as an input, the SPI system interprets this as another Master selecting the SPI as a Slave and starting to send data to it. To avoid bus contention, the SPI system takes the following actions:

1. The MSTR bit in SPCR is cleared and the SPI system becomes a Slave. As a result of the SPI becoming a Slave, the MOSI and SCK pins become inputs.
2. The SPIF Flag in SPSR is set, and if the SPI interrupt is enabled, and the I-bit in SREG is set, the interrupt routine will be executed.

Thus, when interrupt-driven SPI transmission is used in Master mode, and there exists a possibility that $\overline{SS}$ is driven low, the interrupt should always check that the MSTR bit is still set. If the MSTR bit has been cleared by a Slave Select, it must be set by the user to re-enable SPI Master mode.

SPI Control Register – SPCR

Bit	7	6	5	4	3	2	1	0	
	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	SPCR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7 – SPIE: SPI Interrupt Enable**

This bit causes the SPI interrupt to be executed if SPIF bit in the SPSR Register is set and the if the global interrupt enable bit in SREG is set.

- **Bit 6 – SPE: SPI Enable**

When the SPE bit is written to one, the SPI is enabled. This bit must be set to enable any SPI operations.

- **Bit 5 – DORD: Data Order**

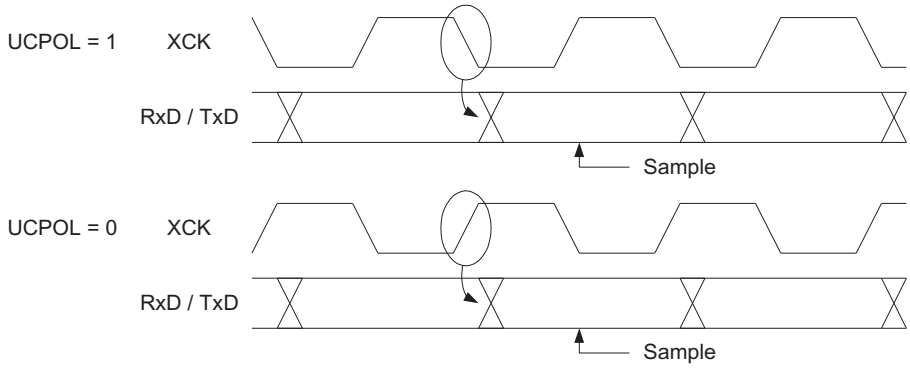
When the DORD bit is written to one, the LSB of the data word is transmitted first.

When the DORD bit is written to zero, the MSB of the data word is transmitted first.

Synchronous Clock Operation

When Synchronous mode is used (UMSEL = 1), the XCK pin will be used as either clock input (Slave) or clock output (Master). The dependency between the clock edges and data sampling or data change is the same. The basic principle is that data input (on RxD) is sampled at the opposite XCK clock edge of the edge the data output (TxD) is changed.

Figure 71. Synchronous Mode XCK Timing.



The UCPOL bit UCRSC selects which XCK clock edge is used for data sampling and which is used for data change. As Figure 71 shows, when UCPOL is zero the data will be changed at rising XCK edge and sampled at falling XCK edge. If UCPOL is set, the data will be changed at falling XCK edge and sampled at rising XCK edge.

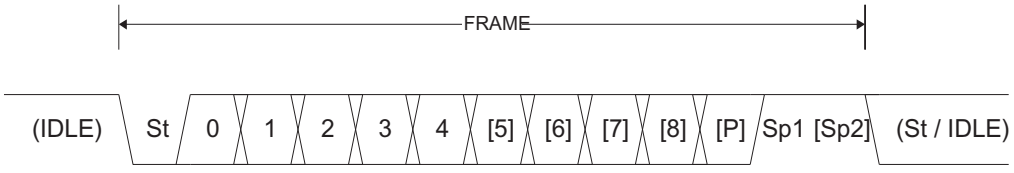
Frame Formats

A serial frame is defined to be one character of data bits with synchronization bits (start and stop bits), and optionally a parity bit for error checking. The USART accepts all 30 combinations of the following as valid frame formats:

- 1 start bit
- 5, 6, 7, 8, or 9 data bits
- no, even or odd parity bit
- 1 or 2 stop bits

A frame starts with the start bit followed by the least significant data bit. Then the next data bits, up to a total of nine, are succeeding, ending with the most significant bit. If enabled, the parity bit is inserted after the data bits, before the stop bits. When a complete frame is transmitted, it can be directly followed by a new frame, or the communication line can be set to an idle (high) state. Figure 72 illustrates the possible combinations of the frame formats. Bits inside brackets are optional.

Figure 72. Frame Formats



St Start bit, always low.

(n) Data bits (0 to 8).

P Parity bit. Can be odd or even.

Sp Stop bit, always high.

Receiving Frames with 9 Databits

If 9 bit characters are used (UCSZ=7) the ninth bit must be read from the RXB8 bit in UCSRB **before** reading the low bits from the UDR. This rule applies to the FE, DOR and PE status Flags as well. Read status from UCSRA, then data from UDR. Reading the UDR I/O location will change the state of the receive buffer FIFO and consequently the TXB8, FE, DOR and PE bits, which all are stored in the FIFO, will change.

The following code example shows a simple USART receive function that handles both 9-bit characters and the status bits.

Assembly Code Example[1]

```
USART_Receive:
  ; Wait for data to be received
  sbis  UCSRA, RXC
  rjmp  USART_Receive
  ; Get status and 9th bit, then data from buffer
  in    r18, UCSRA
  in    r17, UCSRB
  in    r16, UDR
  ; If error, return -1
  andi  r18,(1<<FE)|(1<<DOR)|(1<<PE)
  breq  USART_ReceiveNoError
  ldi   r17, HIGH(-1)
  ldi   r16, LOW(-1)
USART_ReceiveNoError:
  ; Filter the 9th bit, then return
  lsr   r17
  andi  r17, 0x01
  ret
```

C Code Example[1]

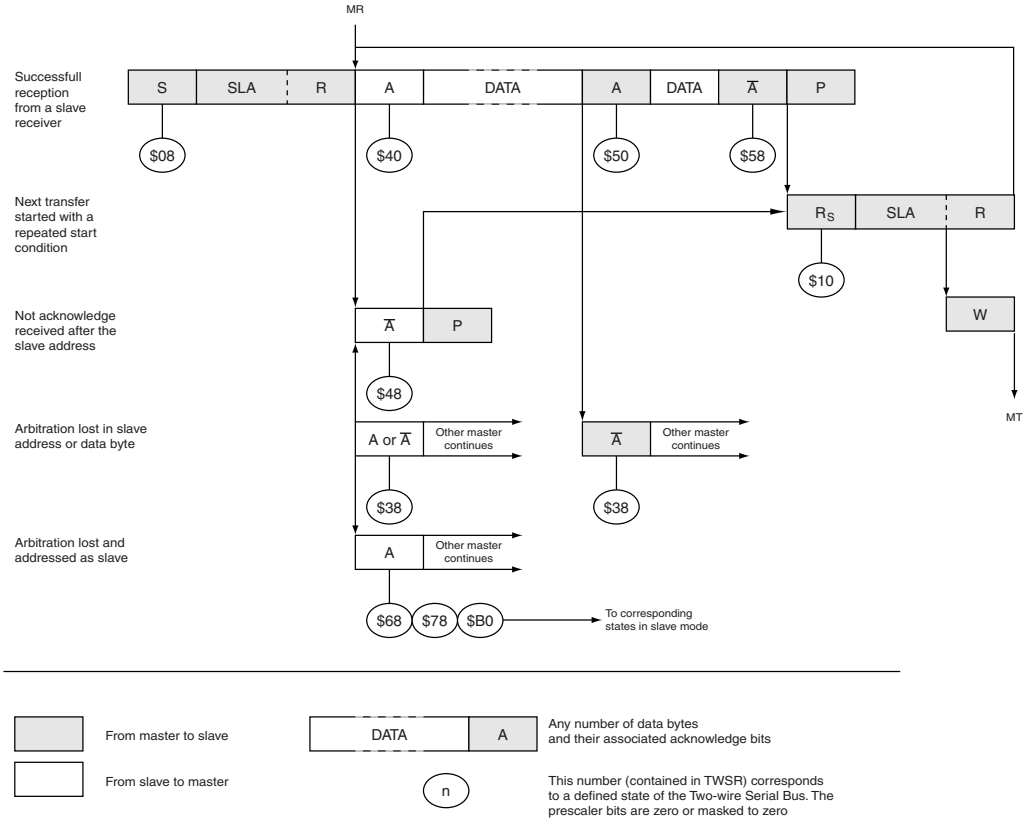
```
unsigned int USART_Receive( void )
{
  unsigned char status, resh, resl;
  /* Wait for data to be received */
  while ( !(UCSRA & (1<<RXC)) )
        ;
  /* Get status and 9th bit, then data */
  /* from buffer */
  status = UCSRA;
  resh = UCSRB;
  resl = UDR;
  /* If error, return -1 */
  if ( status & (1<<FE)|(1<<DOR)|(1<<PE) )
    return -1;
  /* Filter the 9th bit, then return */
  resh = (resh >> 1) & 0x01;
  return ((resh << 8) | resl);
}
```

Note: 1. See “About Code Examples” on page 7.

Table 75. Status Codes for Master Receiver Mode (Continued)

$08	A START condition has been transmitted	Load SLA+R	0	0	1	X	SLA+R will be transmitted ACK or NOT ACK will be received
$10	A repeated START condition has been transmitted	Load SLA+R or Load SLA+W	0 0	0 0	1 1	X X	SLA+R will be transmitted ACK or NOT ACK will be received SLA+W will be transmitted Logic will switch to masTer Transmitter mode
$38	Arbitration lost in SLA+R or NOT ACK bit	No TWDR action or No TWDR action	0 1	0 0	1 1	X X	Two-wire Serial Bus will be released and not addressed Slave mode will be entered A START condition will be transmitted when the bus becomes free
$40	SLA+R has been transmitted; ACK has been received	No TWDR action or No TWDR action	0 0	0 0	1 1	0 1	Data byte will be received and NOT ACK will be returned Data byte will be received and ACK will be returned
$48	SLA+R has been transmitted; NOT ACK has been received	No TWDR action or No TWDR action or No TWDR action	1 0 1	0 1 1	1 1 1	X X X	Repeated START will be transmitted STOP condition will be transmitted and TWSTO Flag will be reset STOP condition followed by a START condition will be transmitted and TWSTO Flag will be reset
$50	Data byte has been received; ACK has been returned	Read data byte or Read data byte	0 0	0 0	1 1	0 1	Data byte will be received and NOT ACK will be returned Data byte will be received and ACK will be returned
$58	Data byte has been received; NOT ACK has been returned	Read data byte or Read data byte or Read data byte	1 0 1	0 1 1	1 1 1	X X X	Repeated START will be transmitted STOP condition will be transmitted and TWSTO Flag will be reset STOP condition followed by a START condition will be transmitted and TWSTO Flag will be reset

Figure 89. Formats and States in the Master Receiver Mode

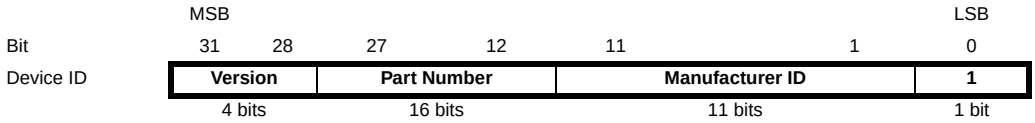


controller state. The Bypass Register can be used to shorten the scan chain on a system when the other devices are to be tested.

Device Identification Register

Figure 114 shows the structure of the Device Identification Register.

Figure 114. The Format of the Device Identification Register



Version

Version is a 4-bit number identifying the revision of the component. The JTAG version number follows the revision of the device. Revision A is 0x0, revision B is 0x1 and so on. However, some revisions deviate from this rule, and the relevant version number is shown in Table 87.

Table 87. JTAG Version Numbers

Version	JTAG Version Number (Hex)
ATmega16 revision G	0x6
ATmega16 revision H	0xE
ATmega16 revision I	0x8
ATmega16 revision J	0x9
ATmega16 revision K	0xA
ATmega16 revision L	0xB

Part Number

The part number is a 16-bit code identifying the component. The JTAG Part Number for ATmega16 is listed in Table 88.

Table 88. AVR JTAG Part Number

Part Number	JTAG Part Number (Hex)
ATmega16	0x9403

Manufacturer ID

The Manufacturer ID is a 11 bit code identifying the manufacturer. The JTAG manufacturer ID for ATMEL is listed in Table 89.

Table 89. Manufacturer ID

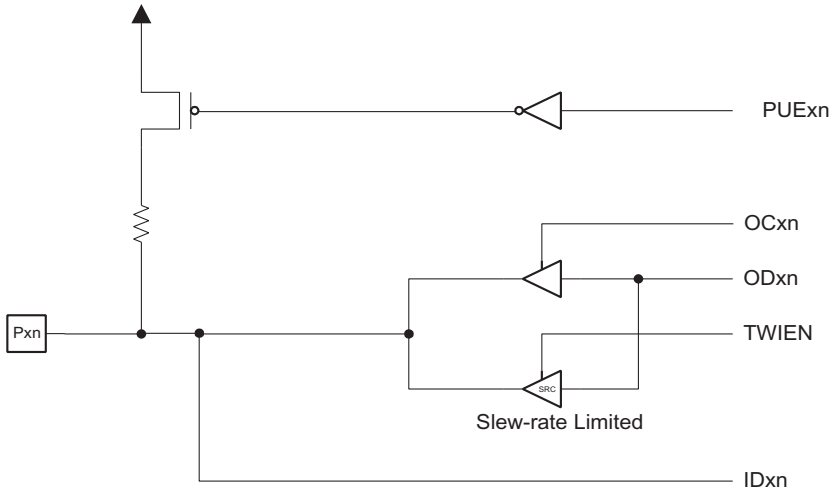
Manufacturer	JTAG Manufacturer ID (Hex)
ATMEL	0x01F

Reset Register

The Reset Register is a Test Data Register used to reset the part. Since the AVR tri-states Port Pins when reset, the Reset Register can also replace the function of the unimplemented optional JTAG instruction HIGHZ.

A high value in the Reset Register corresponds to pulling the External Reset low. The part is reset as long as there is a high value present in the Reset Register. Depending on the Fuse settings for the clock options, the part will remain reset for a Reset Time-Out Period (refer to “Clock Sources” on page 25) after releasing the Reset Register. The output from this Data Register is not latched, so the reset will take place immediately, as shown in Figure 115.

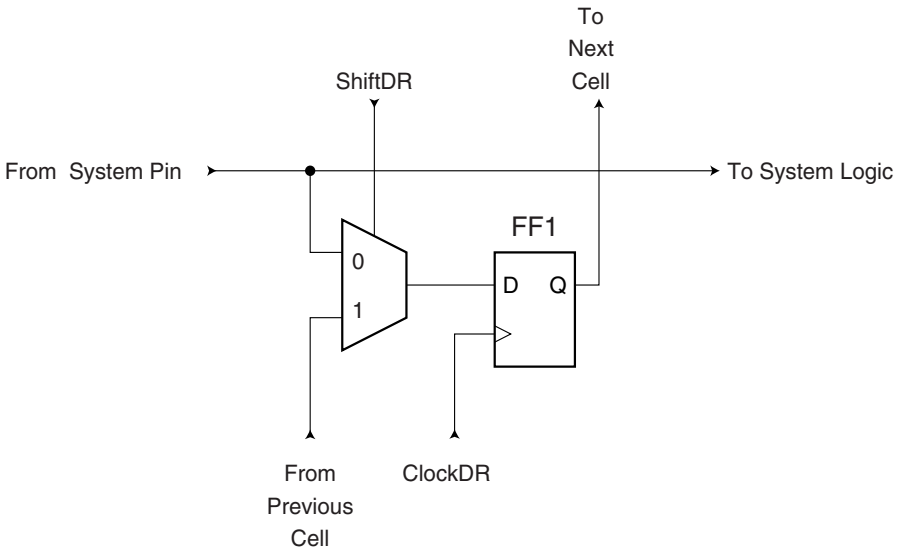
Figure 118. Additional Scan Signal for the Two-wire Interface



Scanning the RESET Pin

The RESET pin accepts 5V active low logic for standard reset operation, and 12V active high logic for High Voltage Parallel Programming. An observe-only cell as shown in Figure 119 is inserted both for the 5V reset signal; RSTT, and the 12V reset signal; RSTHV.

Figure 119. Observe-only Cell



Scanning the Clock Pins

The AVR devices have many clock options selectable by fuses. These are: Internal RC Oscillator, External RC, External Clock, (High Frequency) Crystal Oscillator, Low Frequency Crystal Oscillator, and Ceramic Resonator.

Figure 120 shows how each Oscillator with external connection is supported in the scan chain. The Enable signal is supported with a general boundary-scan cell, while the Oscillator/Clock output is attached to an observe-only cell. In addition to the main clock, the Timer Oscillator is scanned in the same way. The output from the internal RC Oscillator is not scanned, as this Oscillator does not have external connections.

Table 92. Boundary-scan Signals for the ADC (Continued)

Signal Name	Direction as Seen from the ADC	Description	Recommended Input when Not in Use	Output Values when Recommended Inputs are used, and CPU is not Using the ADC
MUXEN_2	Input	Input Mux bit 2	0	0
MUXEN_1	Input	Input Mux bit 1	0	0
MUXEN_0	Input	Input Mux bit 0	1	1
NEGSEL_2	Input	Input Mux for negative input for differential signal, bit 2	0	0
NEGSEL_1	Input	Input Mux for negative input for differential signal, bit 1	0	0
NEGSEL_0	Input	Input Mux for negative input for differential signal, bit 0	0	0
PASSEN	Input	Enable pass-gate of gain stages.	1	1
PRECH	Input	Precharge output latch of comparator. (Active low)	1	1
SCTEST	Input	Switch-cap TEST enable. Output from x10 gain stage send out to Port Pin having ADC_4	0	0
ST	Input	Output of gain stages will settle faster if this signal is high first two ACLK periods after AMPEN goes high.	0	0
VCCREN	Input	Selects Vcc as the ACC reference voltage.	0	0

Note: Incorrect setting of the switches in Figure 123 will make signal contention and may damage the part. There are several input choices to the S&H circuitry on the negative input of the output comparator in Figure 123. Make sure only one path is selected from either one ADC pin, Bandgap reference source, or Ground.

If the ADC is not to be used during scan, the recommended input values from Table 92 should be used. The user is recommended **not** to use the Differential Gain stages during scan. Switch-cap based gain stages require fast operation and accurate timing which is difficult to obtain when used in a scan chain. Details concerning operations of the differential gain stage is therefore not provided.

The AVR ADC is based on the analog circuitry shown in Figure 123 with a successive approximation algorithm implemented in the digital logic. When used in Boundary-scan, the problem is usually to ensure that an applied analog voltage is measured within some limits. This can easily be done without running a successive approximation algorithm: apply the lower limit on the digital DAC[9:0] lines, make sure the output from the comparator is low, then apply the upper limit on the digital DAC[9:0] lines, and verify the output from the comparator to be high.

The ADC need not be used for pure connectivity testing, since all analog inputs are shared with a digital port pin as well.

When using the ADC, remember the following:

- The Port Pin for the ADC channel in use must be configured to be an input with pull-up disabled to avoid signal contention.
- In Normal mode, a dummy conversion (consisting of 10 comparisons) is performed when enabling the ADC. The user is advised to wait at least 200 ns after enabling the ADC before

Table 122. ADC Characteristics (Continued)

Symbol	Parameter	Condition	Min[1]	Typ[1]	Max[1]	Units
V_{INT}	Internal Voltage Reference		2.3	2.6	2.9	V
R_{REF}	Reference Input Resistance			32		kΩ
R_{AIN}	Analog Input Resistance			100		MΩ

Notes: 1. Values are guidelines only.
2. Minimum for AVCC is 2.7V.
3. Maximum for AVCC is 5.5V.

Figure 186. Reset Input Threshold Voltage vs. V_{CC} (V_{IL}, Reset Pin Read As '0')

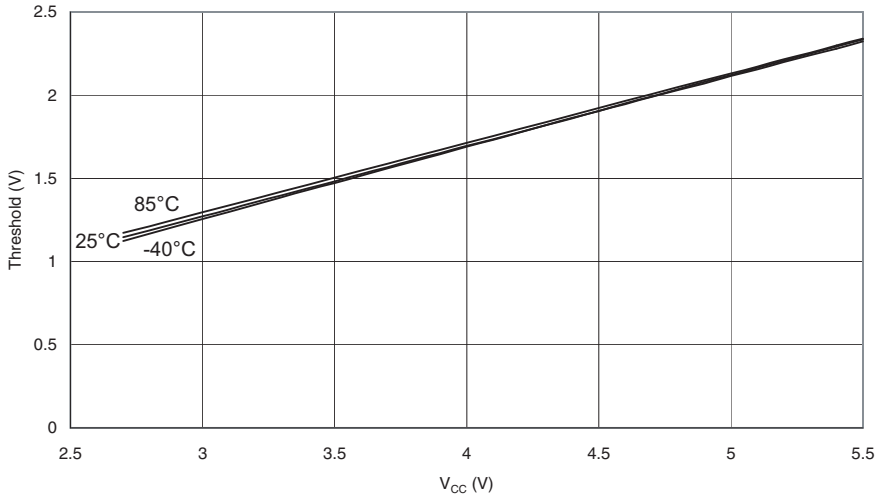
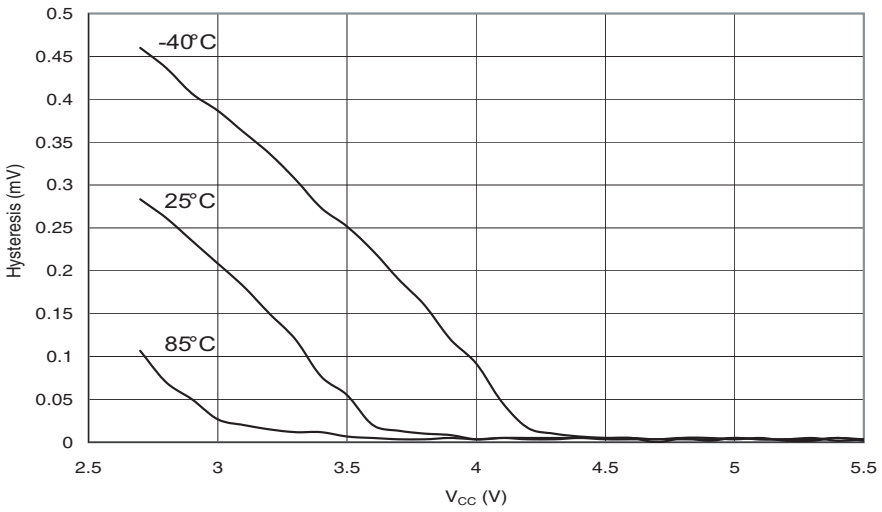


Figure 187. Reset Input Pin Hysteresis vs. V_{CC}



Problem Fix/Workaround

When the device has been powered or reset, disable then enable theAnalog Comparator before the first conversion.

2. **Interrupts may be lost when writing the timer registers in the asynchronous timer**

   The interrupt will be lost if a timer register that is synchronized to the asynchronous timer clock is written when the asynchronous Timer/Counter register(TCNTx) is 0x00.

   Problem Fix / Workaround

   Always check that the asynchronous Timer/Counter register neither have the value 0xFF nor 0x00 before writing to the asynchronous Timer Control Register(TCCRx), asynchronous Timer Counter Register(TCNTx), or asynchronous Output Compare Register(OCRx).

3. **IDCODE masks data from TDI input**

   The JTAG instruction IDCODE is not working correctly. Data to succeeding devices are replaced by all-ones during Update-DR.

   Problem Fix / Workaround

   – If ATmega16 is the only device in the scan chain, the problem is not visible.

   – Select the Device ID Register of the ATmega16 by issuing the IDCODE instruction or by entering the Test-Logic-Reset state of the TAP controller to read out the contents of its Device ID Register and possibly data from succeeding devices of the scan chain. Issue the BYPASS instruction to the ATmega16 while reading the Device ID Registers of preceding devices of the boundary scan chain.

   – If the Device IDs of all devices in the boundary scan chain must be captured simultaneously, the ATmega16 must be the fist device in the chain.

4. **Reading EEPROM by using ST or STS to set EERE bit triggers unexpected interrupt request.**

   Reading EEPROM by using the ST or STS command to set the EERE bit in the EECR register triggers an unexpected EEPROM interrupt request.

   Problem Fix / Workaround

   Always use OUT or SBI to set EERE in EECR.

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- **First Analog Comparator conversion may be delayed**
- **Interrupts may be lost when writing the timer registers in the asynchronous timer**
- **IDCODE masks data from TDI input**
- **Reading EEPROM by using ST or STS to set EERE bit triggers unexpected interrupt request**

1. **First Analog Comparator conversion may be delayed**

   If the device is powered by a slow rising V_{CC}, the first Analog Comparator conversion will take longer than expected on some devices.

   Problem Fix/Workaround

   When the device has been powered or reset, disable then enable theAnalog Comparator before the first conversion.

2. **Interrupts may be lost when writing the timer registers in the asynchronous timer**

   The interrupt will be lost if a timer register that is synchronized to the asynchronous timer clock is written when the asynchronous Timer/Counter register(TCNTx) is 0x00.

9. Added Table 73, “TWI Bit Rate Prescaler,” on page 182 to describe the TWPS bits in the “TWI Status Register – TWSR” on page 181.
10. Added section “Default Clock Source” on page 25.
11. Added note about frequency variation when using an external clock. Note added in “External Clock” on page 31. An extra row and a note added in Table 118 on page 293.
12. Various minor TWI corrections.
13. Added “Power Consumption” data in “Features” on page 1.
14. Added section “EEPROM Write During Power-down Sleep Mode” on page 22.
15. Added note about Differential Mode with Auto Triggering in “Prescaling and Conversion Timing” on page 207.
16. Added updated “Packaging Information” on page 337.

Rev. 2466E-10/02

1. Updated “DC Characteristics” on page 291.

Rev. 2466D-09/02

1. Changed all Flash write/erase cycles from 1,000 to 10,000.
2. Updated the following tables: Table 4 on page 26, Table 15 on page 38, Table 42 on page 85, Table 45 on page 111, Table 46 on page 111, Table 59 on page 143, Table 67 on page 167, Table 90 on page 235, Table 102 on page 258, “DC Characteristics” on page 291, Table 119 on page 293, Table 121 on page 295, and Table 122 on page 297.
3. Updated “Errata” on page 340.

Rev. 2466C-03/02

1. Updated typical EEPROM programming time, Table 1 on page 20.
2. Updated typical start-up time in the following tables:
   Table 3 on page 25, Table 5 on page 27, Table 6 on page 28, Table 8 on page 29, Table 9 on page 29, and Table 10 on page 29.
3. Updated Table 17 on page 43 with typical WDT Time-out.
4. Added Some Preliminary Test Limits and Characterization Data.
   Removed some of the TBD's in the following tables and pages:
   Table 15 on page 38, Table 16 on page 42, Table 116 on page 272 (table removed in document review #D), “Electrical Characteristics” on page 291, Table 119 on page 293, Table 121 on page 295, and Table 122 on page 297.
5. Updated TWI Chapter.
   Added the note at the end of the “Bit Rate Generator Unit” on page 178.
6. Corrected description of ADSC bit in “ADC Control and Status Register A – ADCSRA” on page 219.
7. Improved description on how to do a polarity check of the ADC doff results in “ADC Conversion Result” on page 216.